



### Features

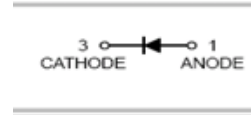
- Low forward voltage drop
- High breakdown voltage
- Guard ring protected
- Low capacitance
- Very small SMD package

### Typical Applications

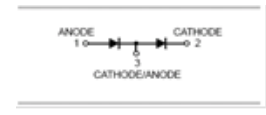
- For high speed switching applications

### Mechanical Data

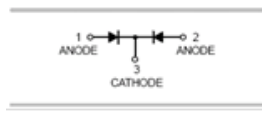
- Case: SOT-323
- Terminals: solderable per MIL-STD-202, Method 208



**BAS70W**



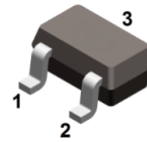
**BAS70W-04**



**BAS70W-05**



**BAS70W-06**



**SOT-323**

### Ordering Information

Part Number	Package	Shipping	Marking Code
BAS70W	SOT-323	3000 pcs / Tape & Reel	K73
BAS70W-04	SOT-323	3000 pcs / Tape & Reel	K74
BAS70W-05	SOT-323	3000 pcs / Tape & Reel	K75
BAS70W-06	SOT-323	3000 pcs / Tape & Reel	K76

### Maximum Ratings (@ T<sub>A</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	70	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Reverse Voltage	V <sub>R</sub>		
Forward Continuous Current *	I <sub>F</sub>	70	mA
Non-Repetitive Peak Forward Surge Current @ t <sub>p</sub> = 8.3ms	I <sub>FSM</sub>	100	mA
Power Dissipation *	P <sub>D</sub>	200	mW

\* part mounted on FR-4 board with recommended pad layout



### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-to-Air <sup>*1</sup>	R <sub>θJA</sub>	390	°C/W
Thermal Resistance Junction-to-Case <sup>*1</sup>	R <sub>θJC</sub>	275	°C/W
Thermal Resistance Junction-to-Lead <sup>*1</sup>	R <sub>θJL</sub>	350	°C/W
Operating Junction Temperature Range	T <sub>J</sub>	-55 ~ +125	°C
Storage Temperature Range	T <sub>STG</sub>	-55 ~ +150	°C

### Electrical Characteristics (@ T<sub>A</sub> = 25°C unless otherwise specified)

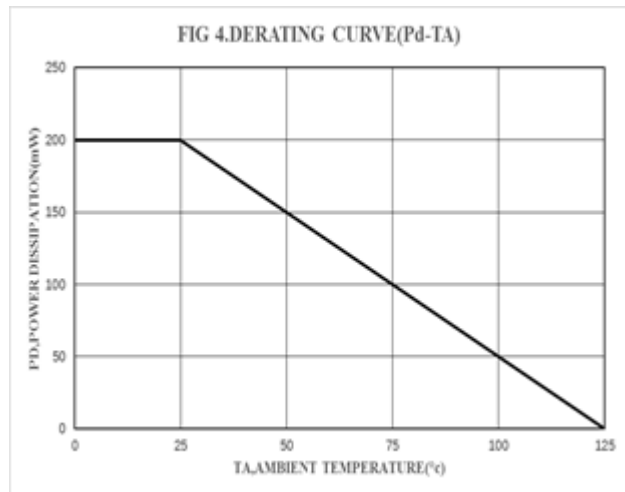
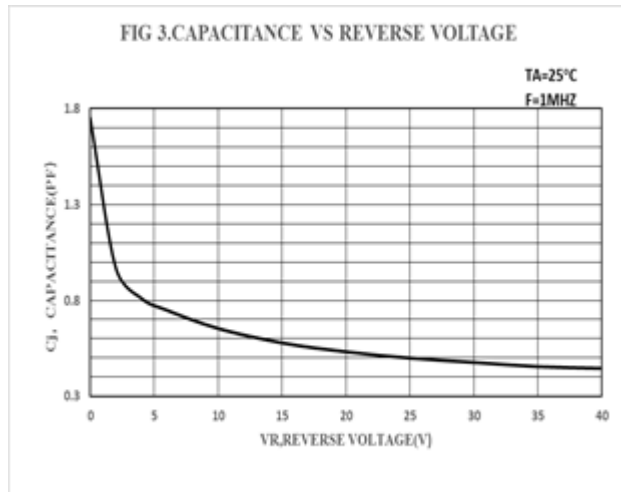
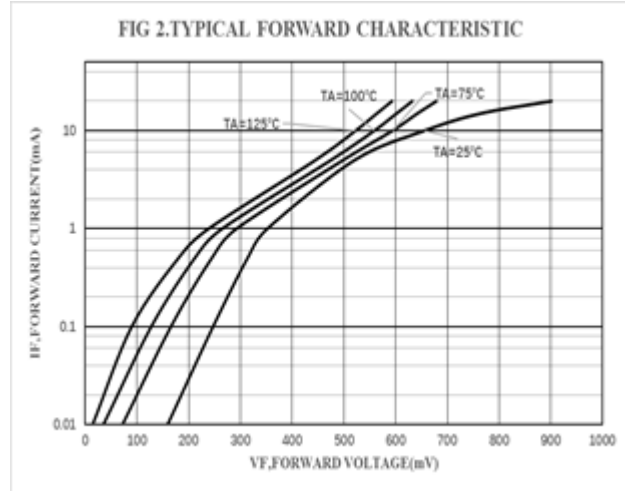
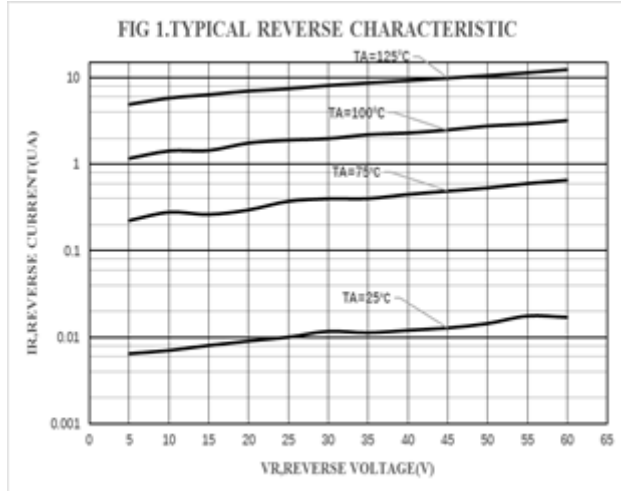
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward Voltage <sup>*2</sup>	V <sub>F</sub>	I <sub>F</sub> = 1mA			0.41	V
		I <sub>F</sub> = 15mA			1	V
Reverse Leakage Current <sup>*3</sup>	I <sub>R</sub>	V <sub>R</sub> = 50V			100	nA
Capacitance Between Terminals	C <sub>T</sub>	V <sub>R</sub> = 0V, f = 1MHz			2	pF
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = I <sub>R</sub> = 10mA, R <sub>L</sub> = 100Ω			5	ns

Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper
2. Pulse test, t<sub>p</sub> ≤ 300μs
3. Pulse test, t<sub>p</sub> ≤ 5ms



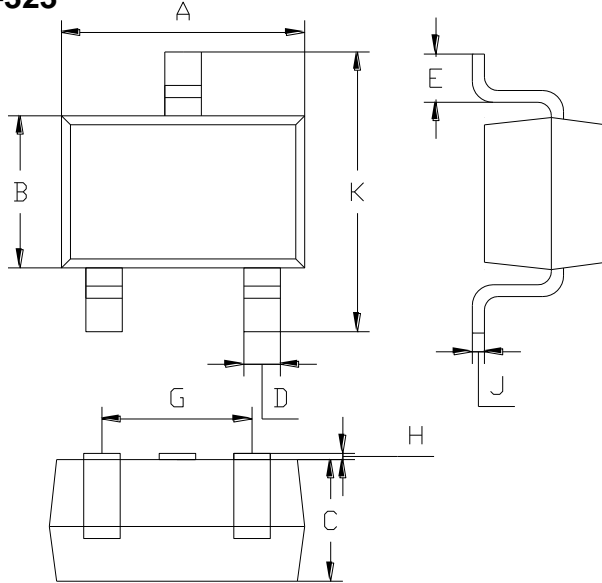
### Ratings and Characteristic Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)





## Package Outline Dimensions (unit: mm)

### SOT-323



SOT-323		
Dim	Min	Max
A	1.80	2.20
B	1.15	1.35
C	0.90	1.10
D	0.15	0.35
E	0.25	0.40
G	1.20	1.40
H	0.02	0.10
J	0.05	0.15
K	2.20	2.40

## Mounting Pad Layout (unit: mm)

### SOT-323

